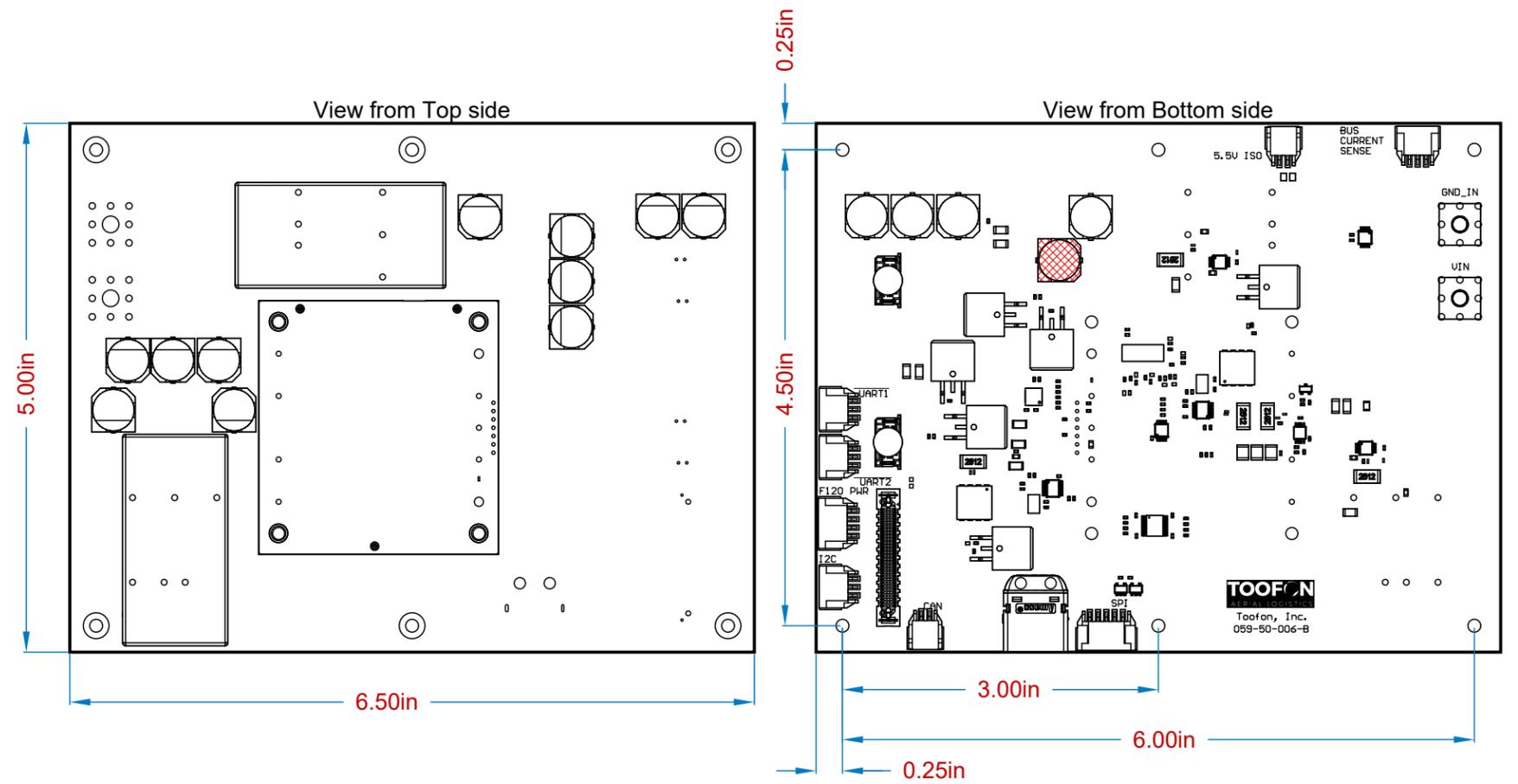


NOTES: UNLESS OTHERWISE SPECIFIED

1. PCB FABRICATION
  - 1.1 PCBs TO BE FABRICATED AS PER IPC-6012 AND MEET IPC-A-600, CLASS 2 REQUIREMENTS.
2. MATERIAL
  - 2.1 PCB DIELECTRIC TO BE ISOLA 370HR OR OTHER EQUIVALENT REQUIRING WRITTEN APPROVAL BY CUSTOMER.
3. SOLDERMASK
  - 3.1 APPLY SOLDER MASK TO BOTH SIDES IAW IPC-SM-840. COLOR BLUE PHOTOIMAGEABLE SOLDERMASK. SOLDER MASK CLEARANCE AROUND COMPONENT PADS SHALL BE .005 MAXIMUM. NO MASK ON PADS ALLOWED.
4. SILKSCREEN
  - 4.1 SILKSCREEN MARKING SHALL BE EITHER USING WHITE EPOXY OR PHOTOIMAGEABLE INK.
  - 4.2 REMOVE ANY SILKSCREEN THAT ENCROACHES ON COMPONENT SOLDER PADS.
  - 4.3 THE PCB WILL HAVE REFERENCE DESIGNATORS AND COMPONENT POLARITY MARKED CLEARLY WITH WHITE SILKSCREEN MARKING.
5. WARP/TWIST/BEND
  - 5.1 BOW OR TWIST SHALL NOT EXCEED 0.75% FOR ALL SMD+TH PCBs.
6. DRILLING
  - 6.1 DRILL BOARDS USING SUPPLIED NC DRILL DATA INCLUDED IN ZIP FILE.
  - 6.2 LAYER TO LAYER MISREGISTRATION SHALL BE WITHIN 0.005".
7. FINISH
  - 7.1 ENIG PER IPC-4552.
  - 7.2 PLATE HOLES THROUGH WITH COPPER 0.001" MINIMUM.
8. ELECTRICAL TESTING
  - 8.1 THE PCBs SHALL BE 100% TESTED FOR CONTINUITY WITHIN A NET AND ISOLATION BETWEEN DIFFERENT NETS TO ENSURE THAT THE FABRICATED PCB NETS MATCH WITH THE SUPPLIED NETLIST DATA.
9. ALL THERMAL VIAS INDICATED IN GERBERS SHALL BE FILLED AND CAPPED (VIA TYPE VII) IAW IPC-4761.

REVISION HISTORY				
REV	DESCRIPTION	DRAWN	APPROVED	APPROVED DATE
B	FIXED ISSUES WITH FETS, CAPS, BUFFER FOOTPRINT	A. Archanian	T. Pailevanian	3/21/2023



Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type	Gerber
Surface Material	Top Overlay			Legend	GTO
Copper	Top Solder	0.40mil	Solder Resist	Solder Mask	GTS
Copper	Top Layer	2.76mil		Signal	GTL
Core		4.33mil	FR-4	Dielectric	
Copper	Signal Layer 1	1.40mil		Signal	G1
Prepreg		47.24mil	FR-4	Dielectric	
Copper	Signal Layer 2	1.40mil		Signal	G2
Core		4.33mil	FR-4	Dielectric	
Copper	Bottom Layer	2.76mil		Signal	GBL
Surface Material	Bottom Solder	0.40mil	Solder Resist	Solder Mask	GBS
	Bottom Overlay			Legend	GBO

Total thickness: 65.02mil

DRAWN		A. Archanian	3/21/2023	 1125 E. Broadway #12 Glendale, CA 91205	
APPROVED		T. Pailevanian	3/21/2023		
<b>INTERMEDIATE BUS CONVERTER MODULE</b>					
SIZE	DWG NO	REV			
B	059-50-006	B			
SCALE: None				SHEET 1 OF 1	

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